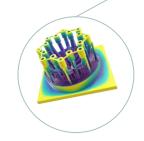
**HIVELIX

Benefits of multiphysics simulation of surface finishing processes of additive manufacturing part by addition or removal technologies

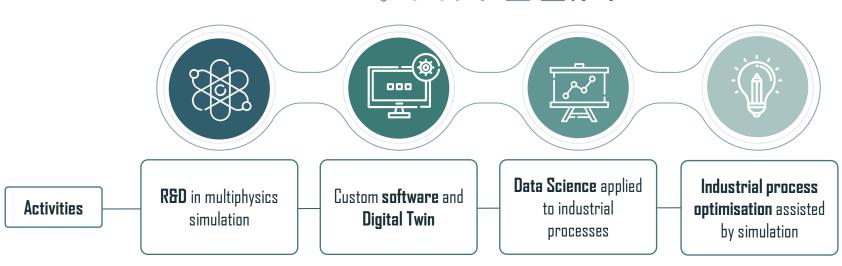




- 1. Additive manufacturing benefits and drawbacks
- 2. Surface finishing processes
- 3. Why model surface finishing processes?
- 4. Electrochemical processes applied to AM parts
- 5. Numerical simulation of chemical etching
- 6. Conclusions



*HIVELIX





Areas of expertise

Electrochemical and chemical engineering (electroplating, electropolishing, anodisation, electrophoresis, chemical etching and plating, corrosion, battery, computational fluid dynamics, granular modeling...)





Industrial sectors

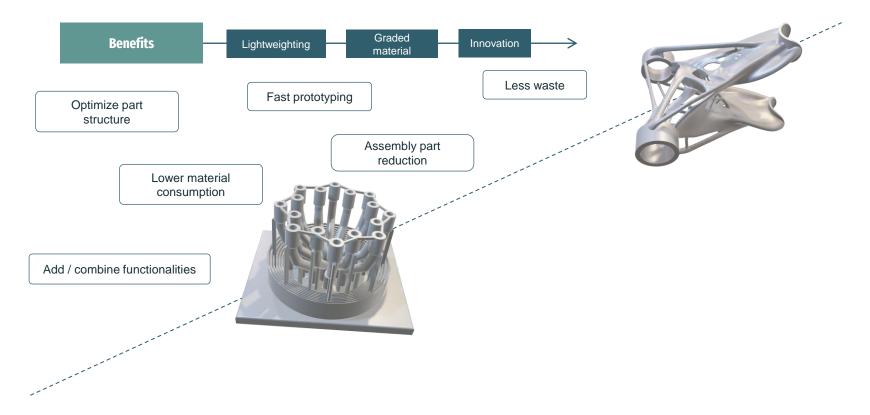
Aeronautic / Luxury / Automotive / Medical / Naval / Military / Electronics / Energy / Nuclear



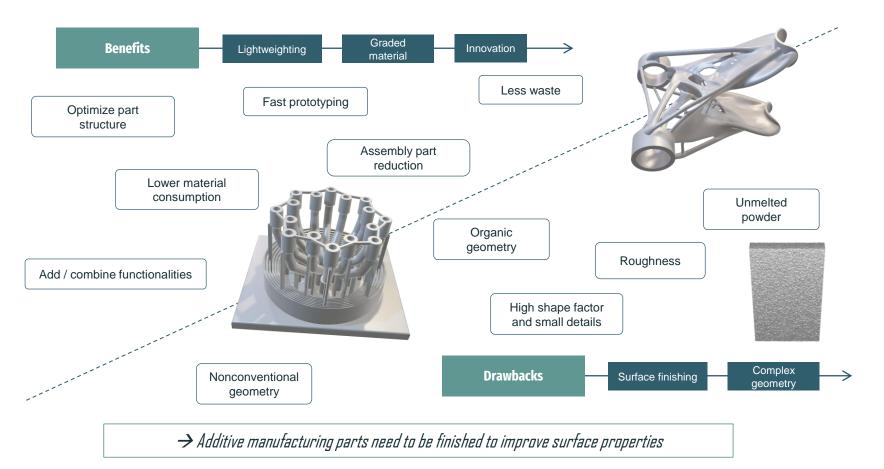




Additive manufacturing : benefits and drawbacks



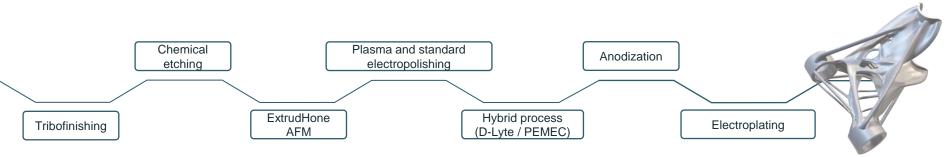
Additive manufacturing : benefits and drawbacks





Surface finishing processes

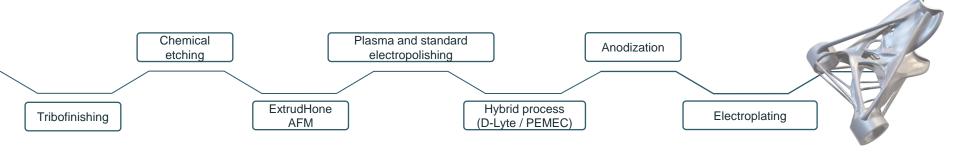
□ Several processes are investigated to improve the surface finish of additive manufacturing parts by adding or removing material.





Surface finishing processes

Several processes are investigated to improve the surface finish of additive manufacturing parts by adding or removing material.

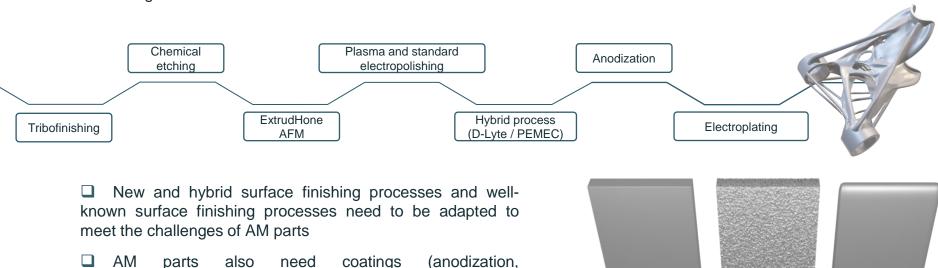


- New and hybrid surface finishing processes and well-known surface finishing processes need to be adapted to meet the challenges of AM parts
- ☐ AM parts also need coatings (anodization, electroplating...) for functional and aesthetic properties
 - → Accessibility on complex geometry parts



Surface finishing processes

Several processes are investigated to improve the surface finish of additive manufacturing parts by adding or removing material.



electroplating...) for functional and aesthetic properties



→ The challenge is to be able to control these processes optimally in order to obtain the good surface roughness while at the same time minimizing shape distortion





Why model surface finishing processes?

Risk of failure to achieve post processing conformity



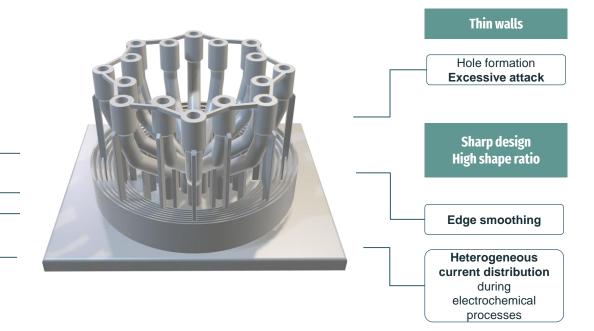
Complex shape / High shape factor

Fluid accessibility and fluid flow during chemical and electrochemical processes

Products removal (unmelted powder, oxide...)

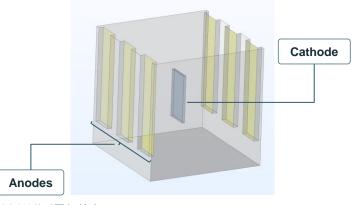
Gas retention during chemical and electrochemical processes

Current line accessibility during electrochemical processes (electroplating, anodization, electropolishing)





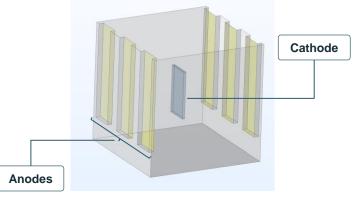
- ☐ Electrochemical processes are intrinsically heterogeneous due to the current distribution inside an electrochemical cell, in case of electroplating, anodization, electropolishing and plasma polishing
- Current distribution and local efficiency depend on many parameters such as process parameters (applied current, treatment duration, T°...), electrolyte chemistry and related properties (conductivity, viscosity, pH...), and fluid flow (mass transport, local concentration).

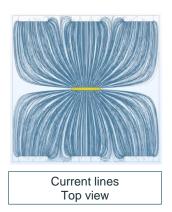


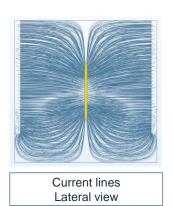




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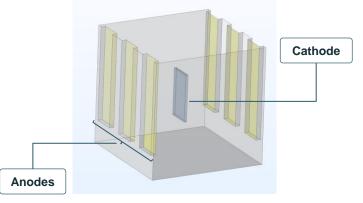


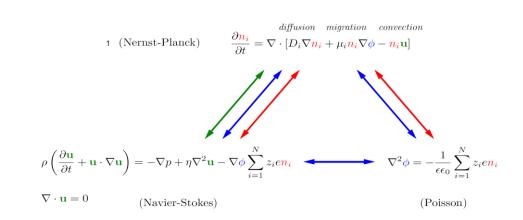


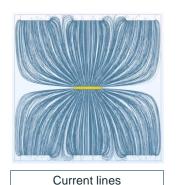


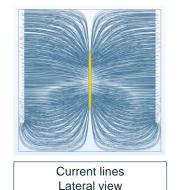


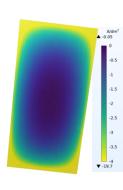
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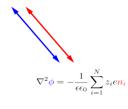




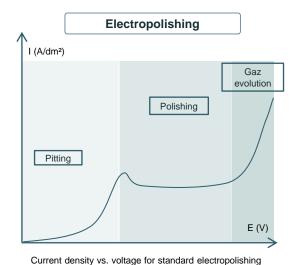


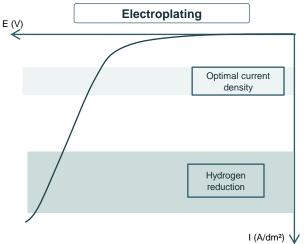
Top view

$$\frac{\partial \mathbf{n_i}}{\partial t} = \nabla \cdot [D_i \nabla \mathbf{n_i} + \mu_i \mathbf{n_i} \nabla \phi]$$



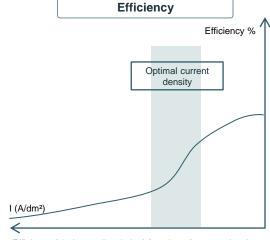
(Poisson)





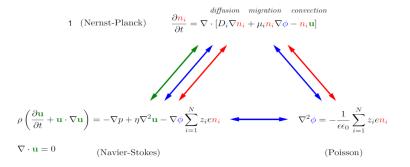
Cathodic curve polarization in electroplating electrolyte (current density vs. voltage)

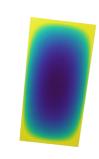
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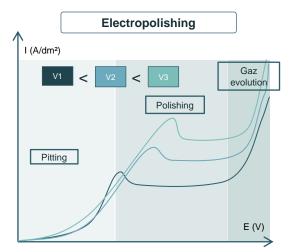


Efficiency (plating or dissolution) function of current density

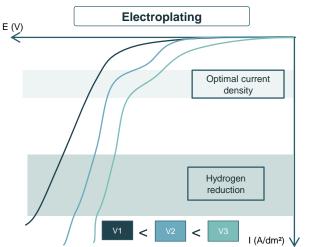




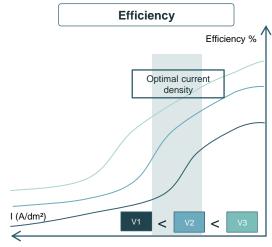




Current density vs. voltage for standard electropolishing in various agitation conditions



Cathodic curve polarization in electroplating electrolyte (current density vs. voltage) in various agitation conditions

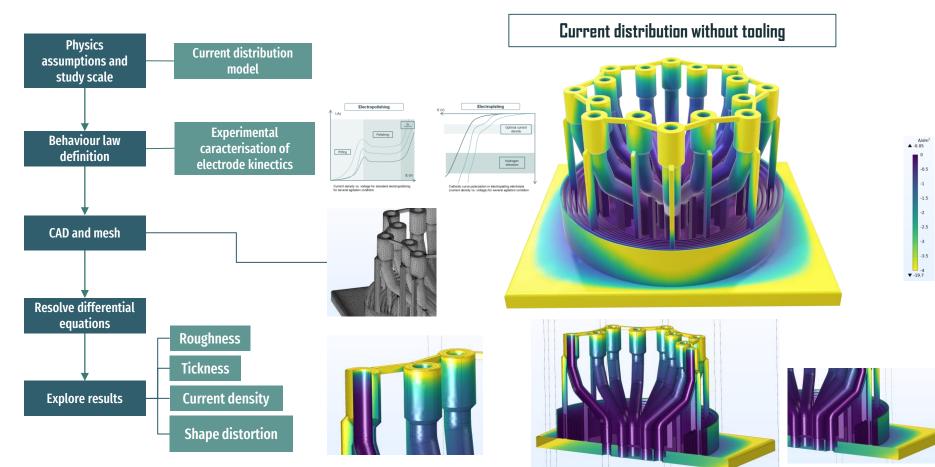


Efficiency (plating or dissolution) function of current density in various agitation conditions

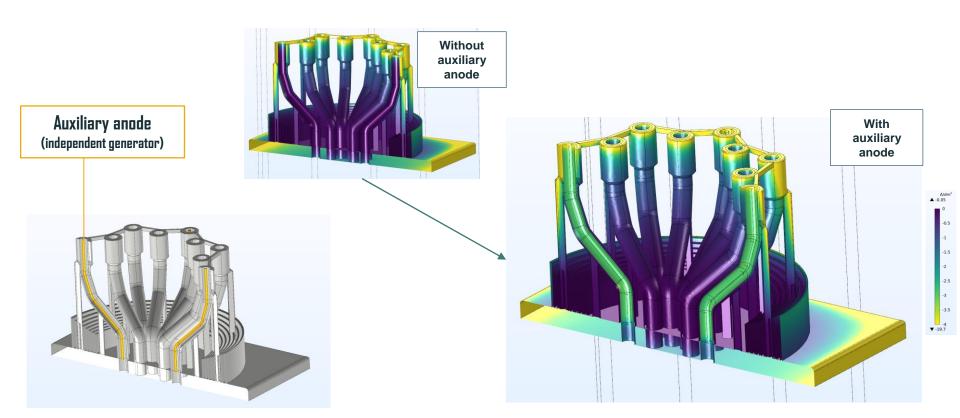
I (A)

1- Direct electrohydrodynamic simulation of electrophoretic particle mobility Tom F.A. Wilms / November 2012 / MTP-1773-A

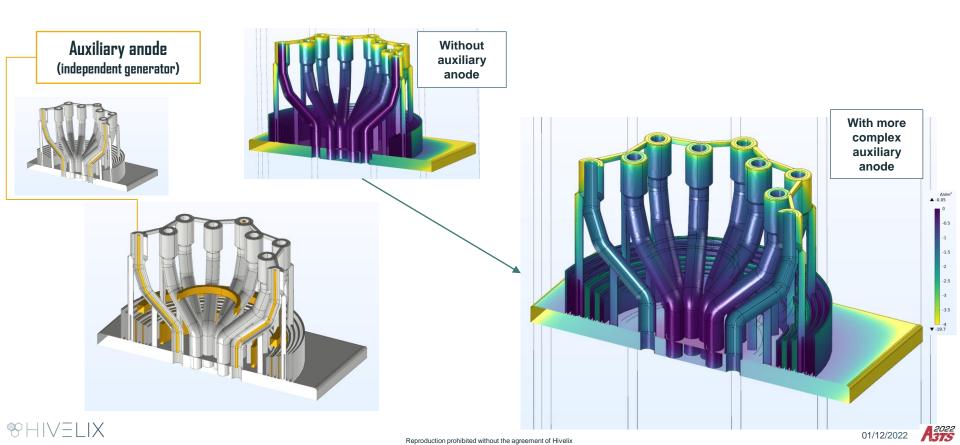




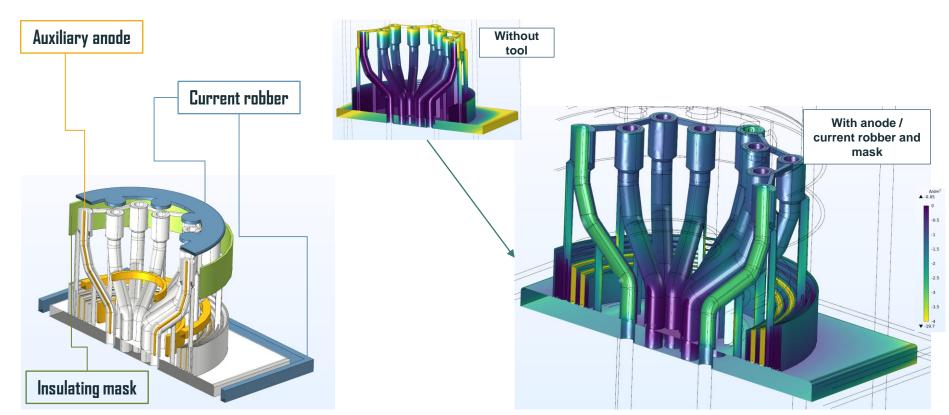
Specific tooling can provide a better current density distribution on complex geometries

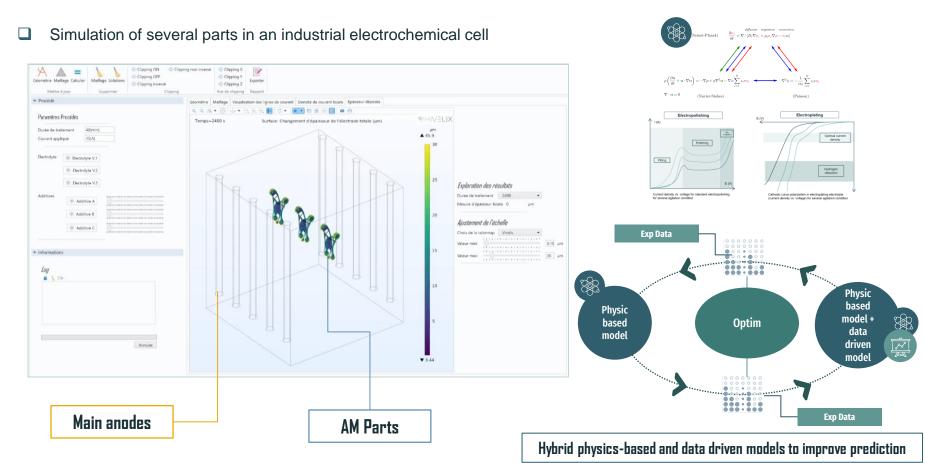


Specific tooling can provide a better current density distribution on complex geometries



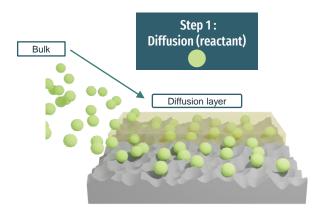
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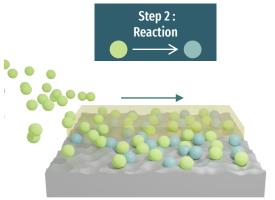


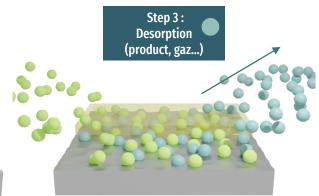


"NEMO" is in the continuance of the AFTER ALM project completed in December 2021, the NExt alM finishing prOcesses project aims to remove important barriers related to the post-processing of complex geometry parts produced by additive manufacturing.

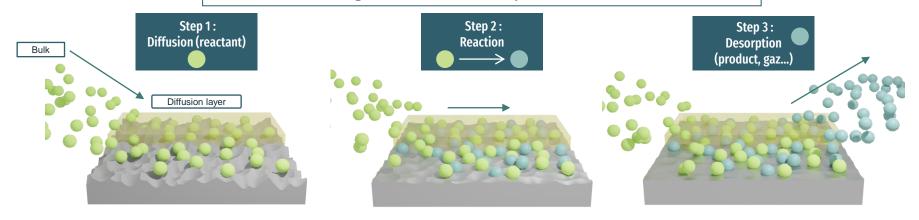
Chemical etching mechanisms







Chemical etching mechanisms \rightarrow Mass transport is the most influential factor



The effective dissolution kinetics is the results of a competition between several phenomena

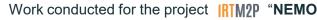
Mass transport of the reactants from the bulk to the surface

Reaction kinetics at the surface function of different parameters (T°, C°, chemistry...)

Mass transport of **products** from the surface (oxides, bubbles...) to the bulk (risk of blocking)

→ Challenge consist of being able to predict mass transport, gas mobility and etching rate

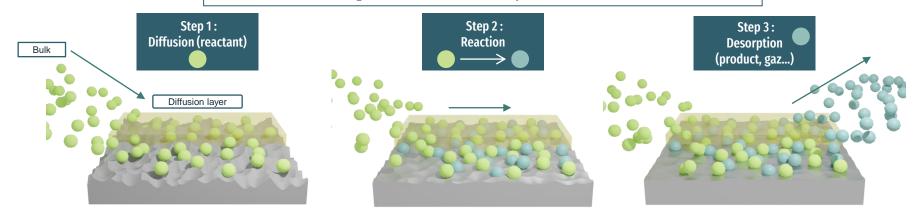




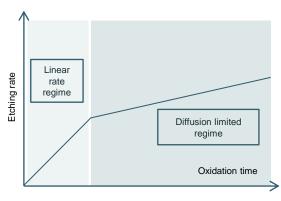




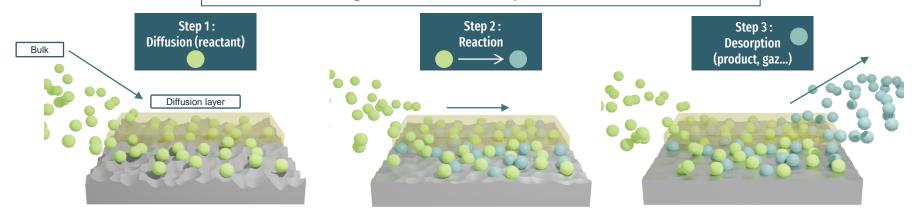
Chemical etching mechanisms \rightarrow Mass transport is the most influential factor



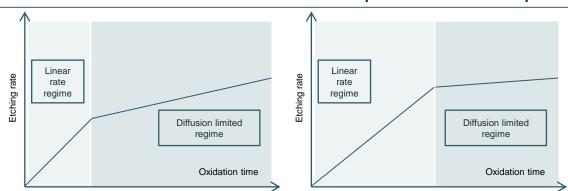
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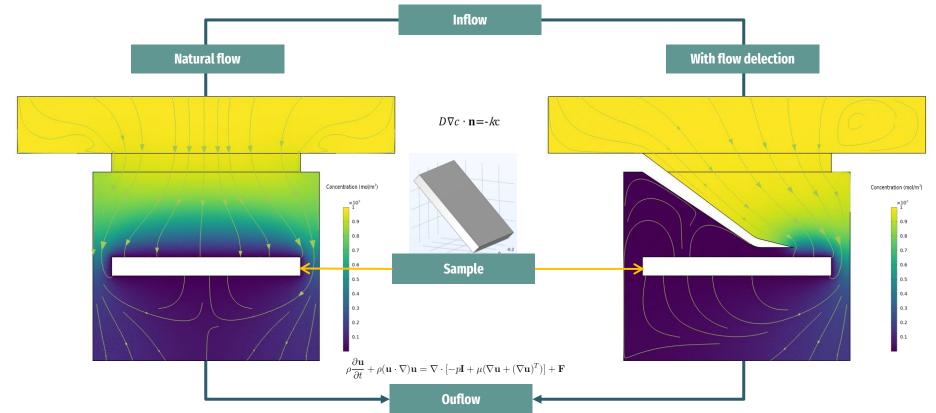
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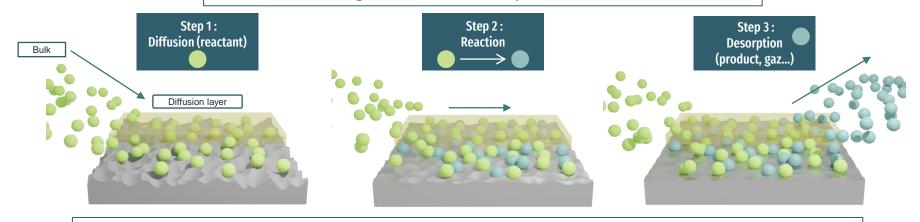




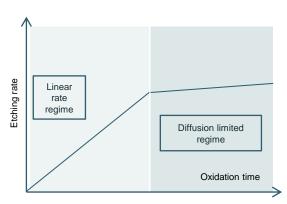
Case study of the transport impact of reactant on the surface:

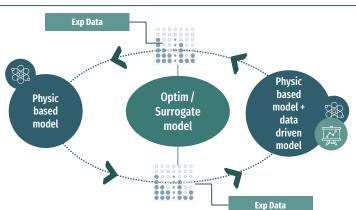


Chemical etching mechanisms \rightarrow Mass transport is the most influential factor



Hybrid physics-based and data driven models to improve prediction rate and identify unknown parameters





Conclusion

→ Reduce time and cost development



- Improve fundamental process understanding
- Improve process management and reduce treatment heterogeneity
- Predict final surface properties in relation to the process parameters applied
- Anticipate shape distortion and oversize parts
- Develop solutions of process control :
 - Fluid flow circulation
 - Designed tools for electrochemical processes
- Hybrid physics-based / data driven models allow to :
 - Complete imperfect physics-based model
 - Increase simulation prediction rate in an industrial environment



Fluid accessibility and fluid flow

Sharp design

Product removal

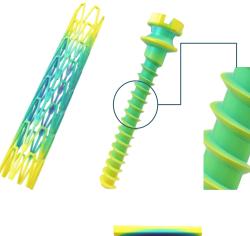
Gas retention

Current lines accessibility

Excessive attack

Edge smoothing

Heterogeneous current distribution









Thank you for your attention

Contact@hivelix.io

Baptiste.fedi@hivelix.io